

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TETSURO NISHIMURA	01/30/2021
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17272246
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DATE SIGNED:	02/26/2021
Total Attachments: 3	
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ASSIGNMENT

I, for good and valuable consideration, receipt of which is hereby acknowledged, have assigned and do hereby assign and sell, which confirms any previous assignment by me or by operation of law, to NIHON SUPERIOR CO., LTD., a Japanese corporation, having its principal place of business at 1-16-15, Esakacho, Suita-shi, Osaka 5640063 Japan ("Assignee"), the entire right, title, and interest, in and to the application for patent entitled

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having Application Number 17/272,246, filed February 26, 2021, and all subject matter and improvements described in said application invented, made, or conceived by me or otherwise owned by me. I further assign to Assignee all patent and all patent convention and treaty rights of all kinds, including the right to claim priority from said application, and all rights in and to any utility model, continuation, continuation-in-part, and divisional application therefrom, and any reissue or re-examination as to any patent issuing from said application, in all countries throughout the world, for all such subject matter described therein. The rights assigned herein include, without limitation all rights of action and rights to recover damages for past infringements and the right to reassign the rights conveyed to Assignee herein. I authorize the USPTO and any other patent office to issue any patent on the above invention or on said application to Assignee. I hereby warrant that I have not executed any other agreement or encumbrance that is in conflict with this Assignment.

I agree that on request and without further consideration, I will communicate to the Assignee or its representatives or nominees any facts known to me respecting the inventions and improvements and testify in any legal proceeding, make all rightful oaths,

sign all lawful papers, and execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights in all countries including, but not limited to, any provisional, non-provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, for any derivation proceedings relating thereto, and, as to any patents that issue from such applications, for any supplemental examination, derivation proceeding, opposition, post grant review, reissue, re-examination, *inter partes* review, or extension thereof, and generally do everything possible to aid the Assignee to obtain, maintain, and enforce proper patent protection for the invention and its improvements in all countries. All of my warranties and covenants stated in this Assignment inure to the benefit of Assignee and any assigns or other successors in interest. I agree to take no future action that is inconsistent with the rights conveyed or agreements made herein.

I hereby further authorize the assignee or its legal representatives to insert the serial number and filing date of the application into this Assignment when this information becomes known.

Legal Name of Inventor:
(Given names first, with Family name last)

Tetsuro NISHIMURA

Inventor's Signature:



Date:

30. Jan. 2021

Inventor's Address:

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